

PRODUCT SPECIFICATION **FOR LCD MODULE**

Revision: 1.0

Model No: LS0395I18-R-V1

Module Type: COG+FPC+B/L

APPROVED SIGNATURE

- ☒ Approved Product Specification only
- ☐ Approved Product Specification and Samples

<u>Prepared By</u>	<u>Checked By</u>	<u>Approved By</u>

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1. General Description

LS0395I18-R-V1 is a transmissive type a-Si TFT-LCD (amorphous silicon thin film transistor liquid crystal display) module, which is composed of a TFT-LCD panel, a driver circuit and a backlight unit. The panel size is 3.95 inch and the resolution is 480(RGB)*480, the panel can display up to 16.7 M colors.

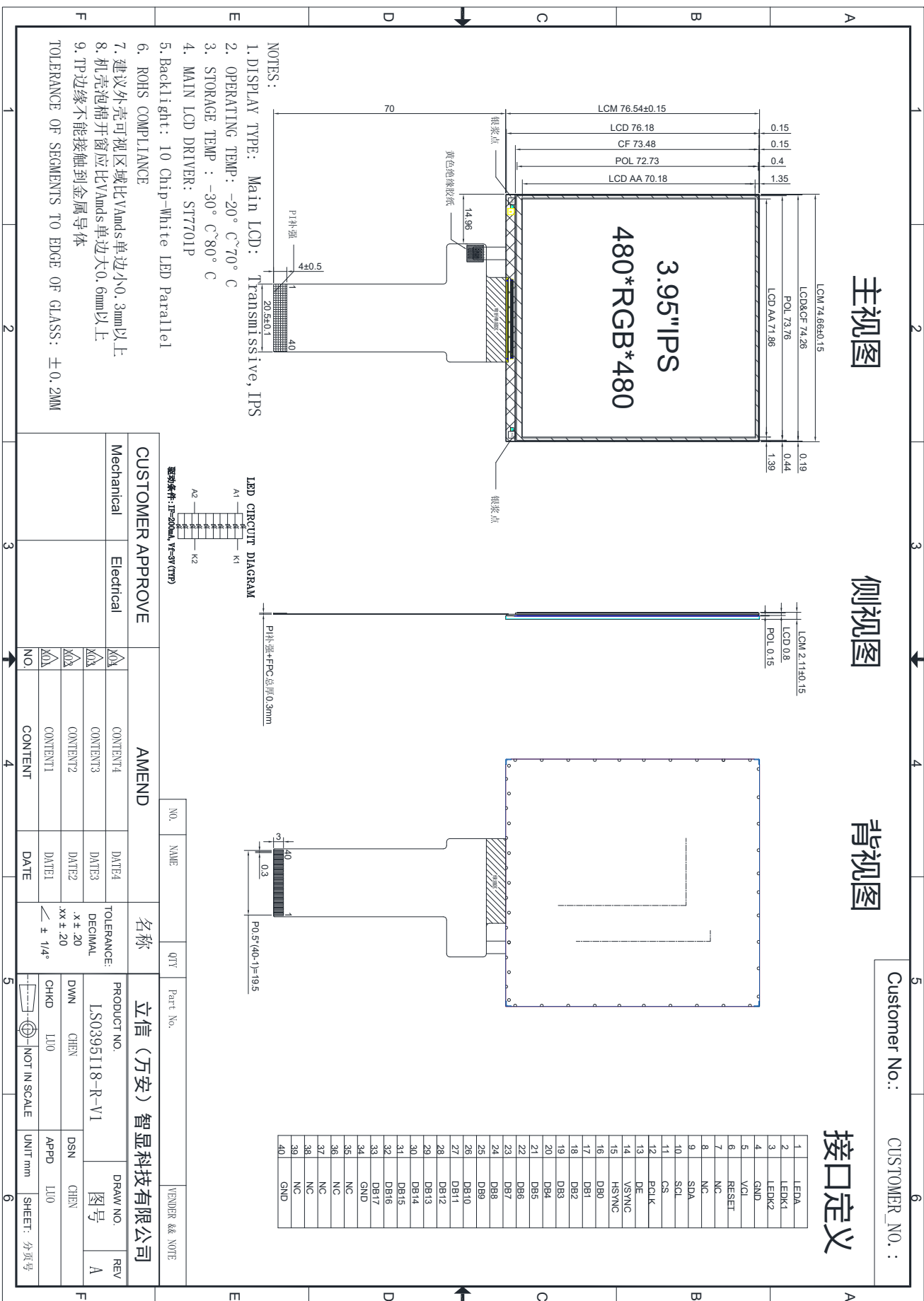
2. Physical Features

Display Mode	TFT-LCD Module
	Active matrix TFT, Transmissive type
Display Format	Graphic 480(RGB)×480 Dot-matrix
Input Data	18BIT RGB
Viewing Direction (Grayscale Inversion)	Free (IPS)
Drive	ST7701P

3. Mechanical Specification

Item	Specification	Unit
Module size (H×V×D)	74.66×76.54×2.11	mm
Number of dots	480(RGB) ×480	pixel
Active area (H×V)	71.86×70.18	mm

4. Outline Dimension



5. Absolute Maximum Ratings

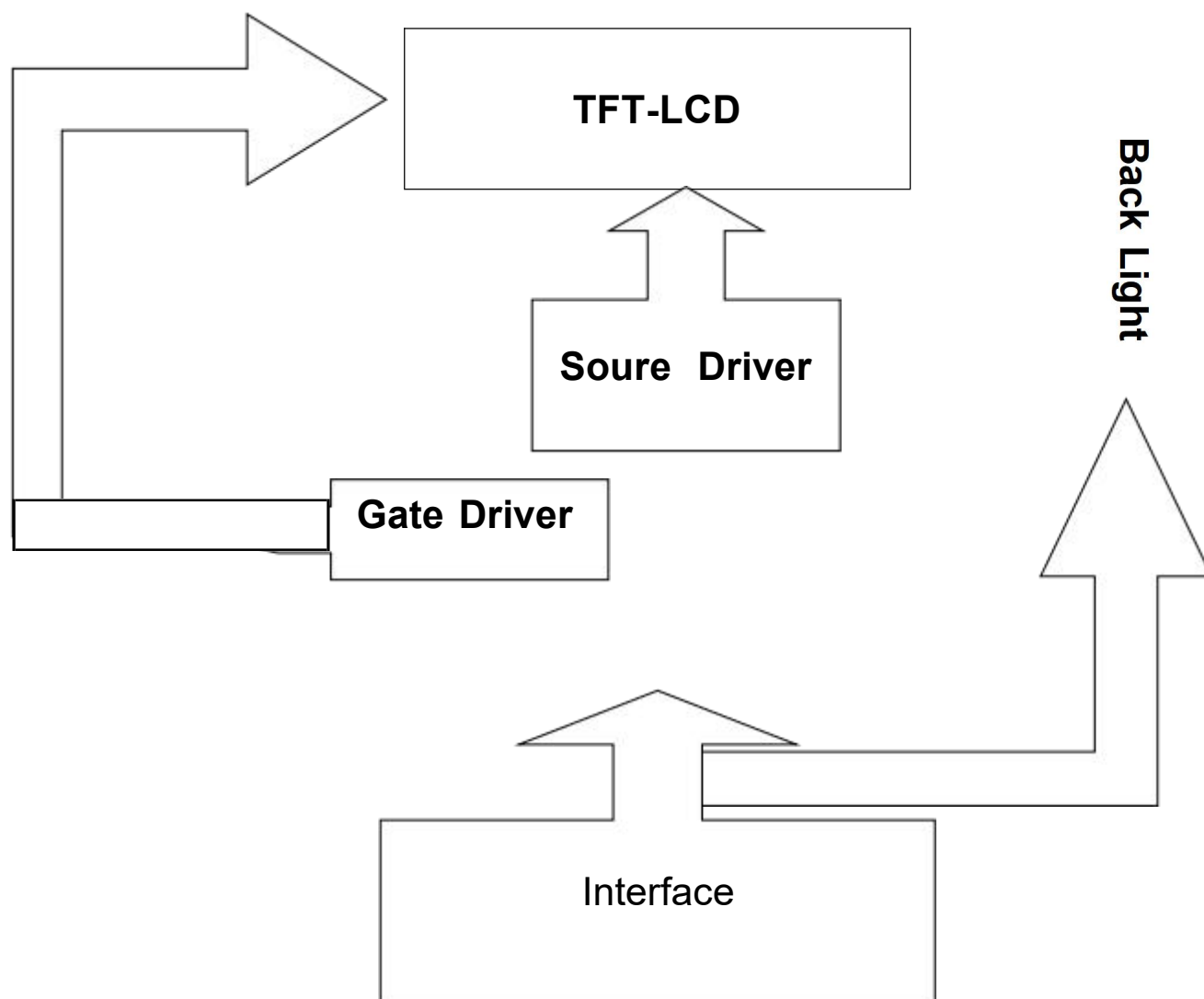
Item	Symbol	Min	Max	Unit	Remark
Supply voltage	VCC	-0.3	3.6	V	Note1 Note2
Supply voltage	IOVCC	-0.3	3.6	V	
Operating temperature	TOPR	-20	70	°C	
Storage temperature	TSTR	-30	80	°C	

6. Electrical Characteristics

Item		Symbol	Rating			Unit	Remark
			Min	Typ	Max		
Supply voltage		VCC	2.5	2.8	3.6	V	Note1
Supply voltage		IOVCC	1.65	1.8	3.3	V	
Input Voltage	L level	VIL	VSS	---	0.3*IOVCC	V	
	H level	VIH	0.7*IOVCC	---	IOVCC	V	

7. Module Function Description

7- 1. Block Diagram Of LCM



7-2. Pin Description

PIN NO.	Symbol	I/O	Description
1	LEDA	P	Power for LED backlight anode
2	LEDK	P	Power for LED backlight cathode
3	LEDK	P	Power for LED backlight cathode
4	GND	P	Ground
5	VCI	P	power supply
6	RESET	I	The external reset input.
7	NC		
8	NC		
9	SDA	I	Serial data input pin used for the SPI Interface. SDI : Serial data input pin
10	SCL	I	The SPI Interface (SCL): Serves as a write signal and writes data at the rising edge. Serial interface (SCL): Serial clock input.
11	CS	I	chip select signal.
12	PCLK	I	Dot clock signal for DPI (RGB) interface operation.
13	DE	I	Data enable signal for DPI (RGB) interface operation
14	VS	I	Frame synchronizing signal for DPI (RGB) interface operation
15	HS	I	Line synchronizing signal for DPI (RGB) interface operation.
16	D0	I	data bus
17	D1	I	data bus
18	D2	I	data bus
19	D3	I	data bus
20	D4	I	data bus
21	D5	I	data bus
22	D6	I	data bus
23	D7	I	data bus
24	D8	I	data bus

25	D9	I	data bus
26	D10	I	data bus
27	D11	I	data bus
28	D12	I	data bus
29	D13	I	data bus
30	D14	I	data bus
31	D15	I	data bus
32	D16	I	data bus
33	D17	I	data bus
34	GND	P	Ground
35	NC		
36	NC		
37	NC		
38	NC		
39	NC		
40	GND	P	Ground

7-3 Timing Characteristics

7.5.1 Serial Interface Characteristics (3-line serial):

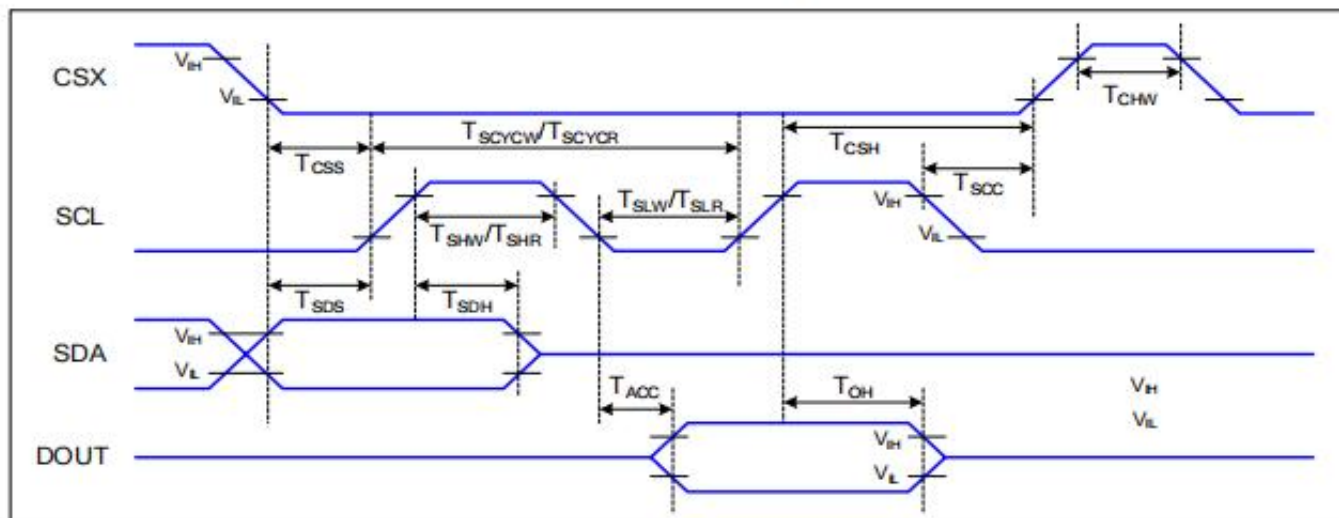


Figure 1 3-line serial Interface Timing Characteristics

VDDI=1.8, VDD=2.8, AGND=DGND=0V, $T_a=25^{\circ}\text{C}$

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	60		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
SDO (DOUT)	T_{ACC}	Access time	20	50	ns	Max: CL=30pF Min: CL=8pF
	T_{OH}	Output disable time	50	50	ns	

7.5.3 RGB Interface Characteristics :

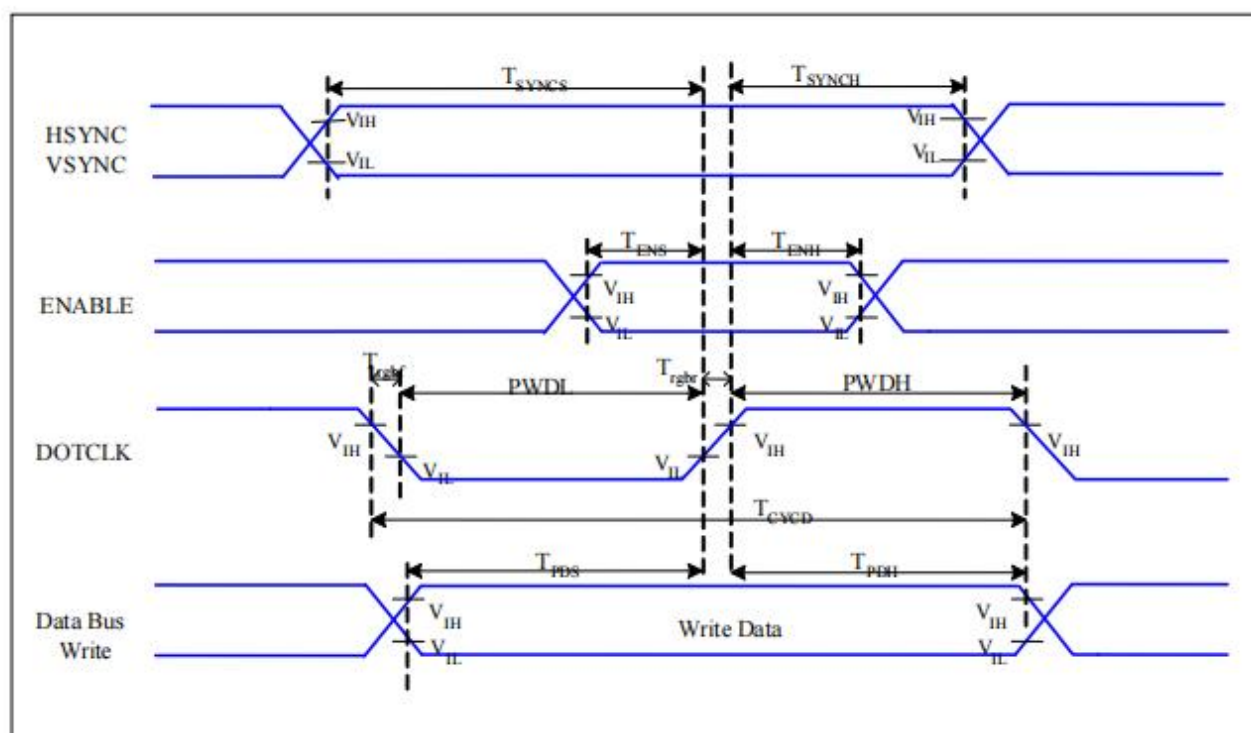


Figure 3 RGB Interface Timing Characteristics

$V_{DDI}=1.8, V_{DD}=2.8, AGND=DGND=0V, T_a=25\text{ }^{\circ}\text{C}$

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYSN, HSYNCS Setup Time	5	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	5	-	ns	
	T_{ENH}	Enable Hold Time	5	-	ns	
DOTCLK	$PWDH$	DOTCLK High-level Pulse Width	15	-	ns	
	$PWDL$	DOTCLK Low-level Pulse Width	15	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	33	-	ns	
	T_{rghf}, T_{rghf}	DOTCLK Rise/Fall time	-	15	ns	
DB	T_{PDS}	PD Data Setup Time	5	-	ns	
	T_{PDH}	PD Data Hold Time	5	-	ns	

Table 6 18/16 Bits RGB Interface Timing Characteristics

8. Electro-Optical Characteristics

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time		Tr +Tf	$\theta_x = \theta_y = 0$	---	30	40	ms	Note 1
Contrast Ratio		CR		640	800	---	---	Note 2
Transmittance		T%		5.0	5.5	---	%	
Color Chromaticity (CIE1931)	White	W x	$\theta_x = \theta_y = 0$	---	0.301	---	---	
		W y		---	0.327	---	---	
Viewing angle	θ_T		CR > 10	---	80	---	Deg.	Note 3
	θ_B			---	80	---		
	θ_L			---	80	---		
	θ_R			---	80	---		

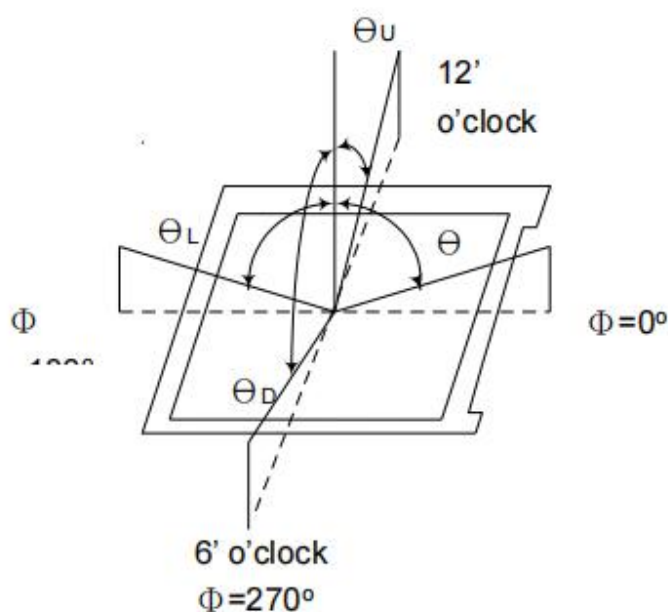
4.2 Measuring Condition

- Measuring surrounding : dark room
- Ambient temperature : $25 \pm 2^\circ\text{C}$
- 15min. warm-up time.

4.3 Measuring Equipment

- FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

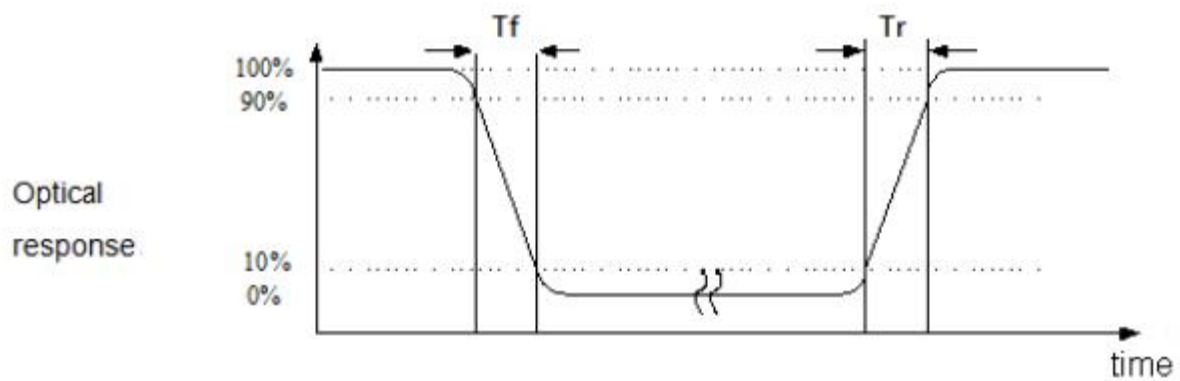
Note (1) Definition of Viewing Angle:



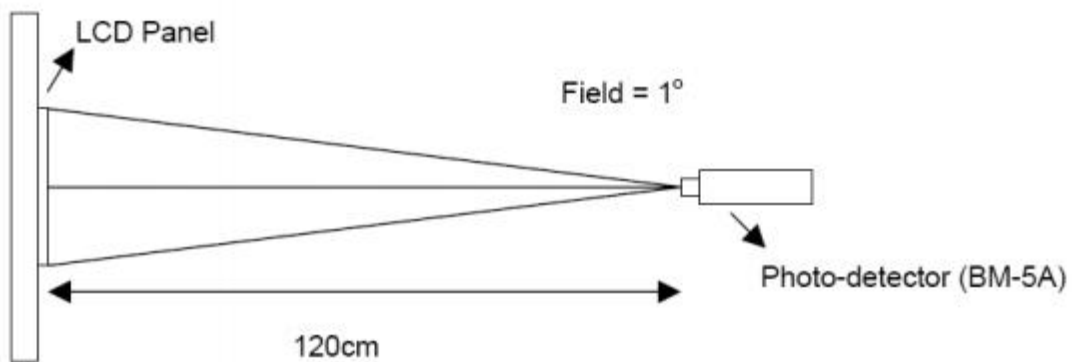
Note (2) Definition of Contrast Ratio (CR) :
measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

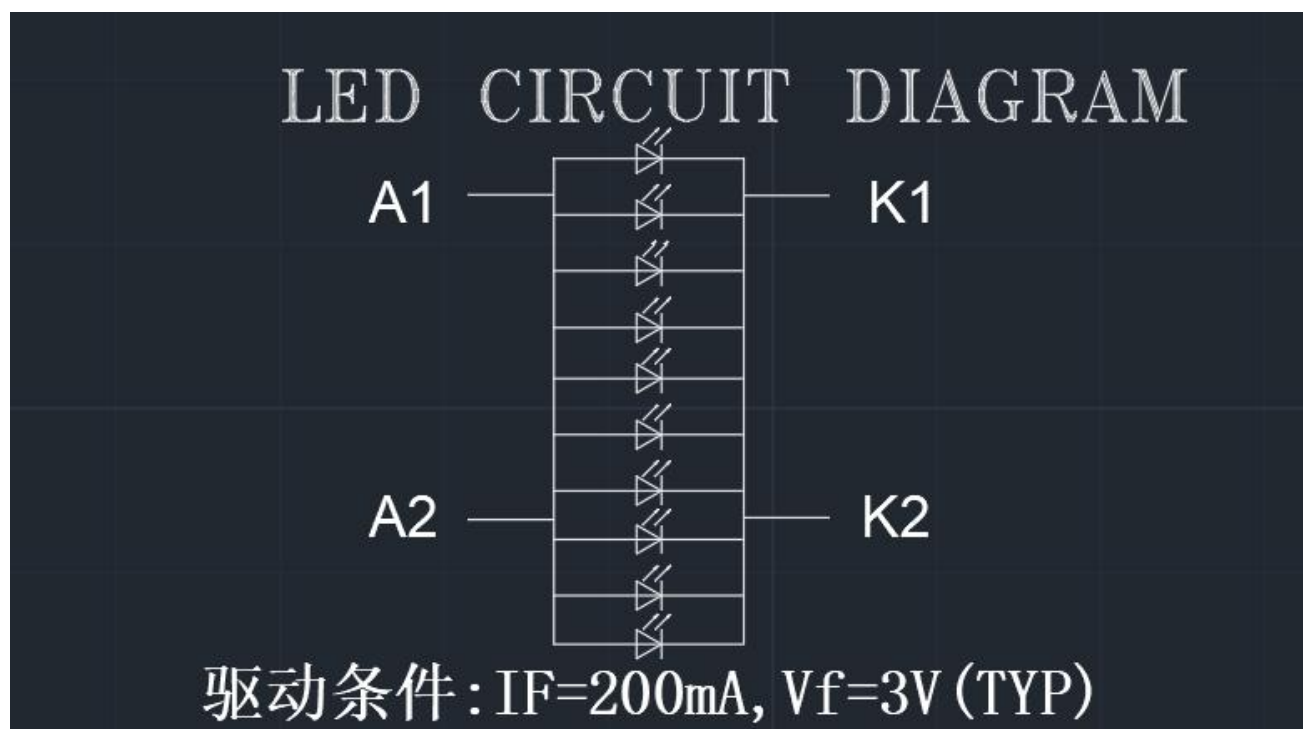
Note (3) Definition of Response Time : Sum of T_R and T_F



Note (4) Definition of optical measurement setup



Note(4) Backlight circuit



9. Inspection Standards

1. AQL(Acceptable Quality Level)

AQL of major and minor defect

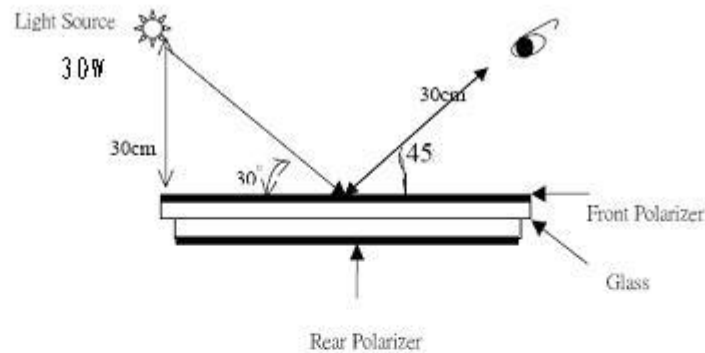
According to GB/T 2828-2003 ; , normal inspection, Class II

MAJOR DEFECT	MINOR DEFECT
0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, About an angle of incidence 30°, a distance of 30cm with normal eye, with an angle of 45° degree to check the products without uncovering the film!

(As shown below)

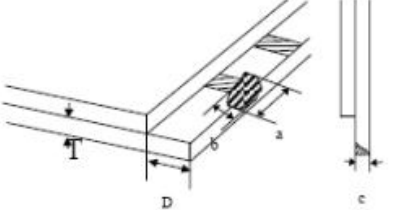
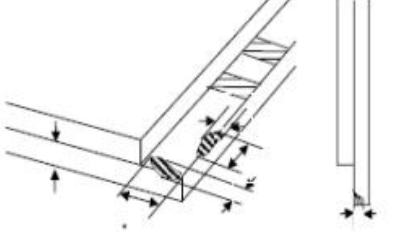


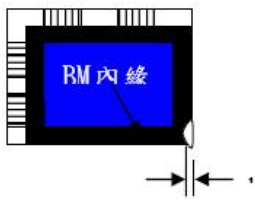
3. Inspection item and criteria

3.1 Visual inspection criterion in immobility

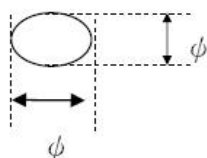
3.1.1 Glass defect

No	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	

No	Defect item	Criteria	Remark
2	Cracks (Major defect)	1.Linear cracks on panel 【Reject】 2. Nonlinear crack contrast by limited sample	
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage 1) $b \leq 1/3$ Pin width(non bonding area) 【Accept】 2) bonding area $\leq 0.5\text{mm}$ 【Accept】	a:Length, b:Width
4	Pin-side , conductive area damaged (minor defect)	(a c : disregards) $b \leq 1/3$ of effective length for bonding electrode 【Accept】	a:Length, b: Width, c: Thickness  The diagram shows a cross-section of a panel with a pin. A shaded area represents the damaged conductive region. Dimensions are labeled: 'a' for the length of the damaged area along the pin, 'b' for the width of the damaged area, and 'c' for the thickness of the panel. A vertical line 'D' indicates the pin position.
5	Pin-side , non-conductive area damaged (minor defect)	1) Damage area don't touch the ITO (Inclueing contraposition mark,except scribing mark) 【Accept】 2) $c < T$ $b \leq BM 1/3$ of width 【Accept】 3) $c = T$ b not touch the seal glue 【Accept】 4) a disregards	a:Length, b: Width, c: Thickness  The diagram shows a cross-section of a panel with a pin. A shaded area represents the damaged non-conductive region. Dimensions are labeled: 'a' for the length of the damaged area along the pin, 'b' for the width of the damaged area, and 'c' for the thickness of the panel. A vertical line 'D' indicates the pin position.

No	Defect item	Criteria	Remark
6	Non-pin-side damage (minor defect)	$c < T$ 1) b exceeds 1/3 BM 【Reject】	c : Thickness b: width of damage 
		$c = T$ b not touch the seal glue 【Reject】	

3.1.2 LCD appearance defect (View area)

No	Defect item	Criteria		Remark
1	Fiber 、 glass cratch 、 polarizer scratch/folded (minor defect)	Specification	Allowable	note1: L : Length , W : Width note2: disregard if out of AA 
		$0.05\text{mm} < W \leq 0.1\text{mm};$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm}; L > 3.0\text{mm}$	0	
2	Polarizer bubble 、 concave and convex (minor defect)	$\psi \leq 0.2\text{mm}$	disregard	note 1: $\psi = (L+W)/2$; L : Length , W : Width note2: disregard if out of AA
		$0.2\text{mm} < \psi \leq 0.3\text{mm}$	2	
		$0.3\text{mm} < \psi \leq 0.5\text{mm}$	1	
		$0.5\text{mm} < \psi$	0	
3	Black dots 、 dirty dots 、 impurities 、 eyewinker (Major defect)	$\psi \leq 0.15\text{mm}$	disregard	note2: disregard if out of AA 
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
4	Polarizer prick (Major defect)	$\psi \leq 0.1\text{mm}$	disregard	note1: $\psi = (L+W)/2$; L= Length , W=Width note2: the distance between two dots > 5mm
		$0.1\text{mm} < \psi \leq 0.25\text{mm}$	3	
		$\psi > 0.25\text{mm}$	0	

3.1.3 .FPC

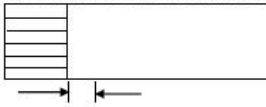
No	Defect item	Criteria		Remark
1	Copper screen peel (Major defect)	Copper screen peel 【 Reject】		
2	No release tape or peel (Major defect)	No release tape or peel 【 Reject】		
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	note1: Cannot have stride ITO impurities
		$\psi \leq 0.25\text{mm}$	2	
		$\psi > 0.25$	0	

3.1.4 Black tape & Mara tape

1	FPC or H/S black tape shift (minor defect)	1.shift spec: 1)glue to the polarize 【 Reject】 2) IC bare 【 Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【 Reject】 2)IC bare 【 Reject】	
2	No black tape (Major defect)	No black tape 【 Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing 【 Reject】	
4	Mara tape defect (minor defect)	Peel before pulling the protecting film. 【 Reject】	

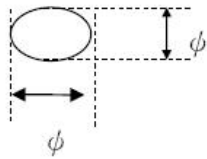
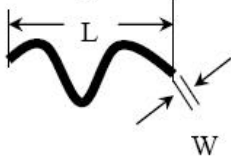
3.1.5 Silicon and Tuffy glue

No	Defect item	Criteria	Remark
1	Quantity of silicon (minor defect)	Uncover the ITO and circuit area. 【 Reject】	note: compared by engineering drawing.

No	Defect item	Criteria	Remark
2	Tuffy glue (minor defect)	1. Uncover the reveal copper area 【 Reject】 2. Cover layer 0.3mm(Min) ~ 3.0mm(Max) 【 accept】	note:if customer has special requirement , refer to the technical document. 
3	Depth of glue covering (minor defect)	Depth of glue covering overtop front Polarizer 【 Reject】	Except of the special requirement °

3.2 Electrical criteria

No	Defect item	Criteria	Remark
1	No display (Major defect)	No display 【 Reject】	
2	Missing line (Major defect)	Missing line 【 Reject】	
3	Seg-com light and dark (Major defect)	Seg-com light and dark 【 Reject】	ND filter 2% test
4	No display in immobility (Major defect)	No display in immobility 【 Reject】	
5	Flicker of Pattern (Major defect)	Flicker of Pattern 【 Reject】	
6	Mura (Major defect)	ND filter 2% test	
7	Over current (Major defect)	Over current 【 Reject】	
8	Voltage out of specification (Major defect)	Voltage out of specification 【 Reject】	
9	Pattern blur ,error code (Major defect)	Pattern blur ,error code 【 Reject】	
10	Dark light, Flicker (Major defect)	Dark light, Flicker 【 Reject】	

No	Defect item	Criteria	Remark	
11	Black/White dots 、 Dirty dots 、 eyewinker (Major defect)	Specification	Allowable	Note1: disregard if out of AA 
		$\psi \leq 0.15\text{mm}$	disregard	
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
12	Fiber 、 glass cratch 、 polarizer scratch/folded (minor defect)	$W \leq 0.03\text{mm}$	disregard	note1: L : Length 、 W : Width note2: disregard if out of AA 
		$0.03\text{mm} < W \leq 0.05\text{mm} ;$ $L \leq 3.0\text{mm}$	2	
		$0.05\text{mm} < W \leq 0.1\text{mm} ;$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm} ; L > 3.0\text{mm}$	0	

10.Records Of Version

Version	Revise Date	Page	Content
00	2026-5-25	all	New released